

Amendments to the Specification

(1) Please replace Paragraphs [0019] to [0023] with the following amended paragraphs:

[0019] FIG. [[4A]] 4 is a schematic diagram showing the heat sink linked with the circuit board of the invention.

[0020] FIG. [[4B]] 5 is a cross-sectional view taken along the line [[A – A']] 5 – 5 of FIG. [[4A]] 4.

[0021] FIG. [[5]] 6 is a schematic diagram showing the circuit board according to the third embodiment of the invention.

[0022] FIG. [[6]] 7 is a schematic diagram showing the circuit board according to the fourth embodiment of the invention.

[0023] FIG. [[7]] 8 is a schematic diagram showing the circuit board according to the fifth embodiment of the invention.

(2) Please replace Paragraphs [0024] and [0027] with the following amended paragraphs:

[0024] FIG. 1 is a schematic diagram showing the circuit board according to the first embodiment of the invention, and FIG. 2 is a schematic diagram showing a fan provided with the circuit board. As shown in FIGs. 1 and 2, a fan structure 200 of the invention includes a hub 202, a motor 120 located inside the hub 202, a plurality of fan blades 204 connected to the hub 202, and a circuit board 100 connected to the motor 120.

[0025] The hub 202 is coupled to the motor 120 so as to rotate synchronously with the motor 120 and drive the fan blades 204 to rotate accordingly. When the fan blades 204 rotate, an airflow flowing through the

fan structure 200 is generated.

[0026] It should be understood that the various shapes and materials of the hub 202, motor 120, and the fan blades 204 can be chosen to meet the actual requirements. It will be obvious, however, to one skilled in the art, that the present invention may be practiced without some or all of these specific details. In other instances, the specific details have been omitted to avoid misinterpretation of the present invention.

[0027] The circuit board 100 comprises a circuit region 102 and a heat-dissipative film 106, wherein the heat-dissipative film 106 is located on the edge of the circuit board 100. The circuit region 102 includes circuits, semiconductor devices, integrated circuits and related components for driving the motor 120 connected to the circuit board 100. Some of the components, such as the integrated circuit and semiconductor devices, can be grouped into a heat-generating component 104.

(3) Please replace Paragraphs [0033] to [0036] with the following amended paragraphs:

[0033] Alternatively, as shown in FIGs. [[4A]] 4 and [[4B]] 5, the heat sink 302 is engaged with the circuit board 300 by sheet-metal working and connected with the heat-dissipative film 106. For instance, a fastening portion 304 is formed on the heat sink 302, and then the heat sink 302 is directly engaged with the circuit board 300 via clamping or fastening and then connected to the heat-dissipative film 106 through the fastening portion 304.

[0034] Moreover, as shown in FIG. [[5]] 6, the circuit board 400

is provided with a protrusion 110, wherein a heat-generating component 104 is located on the protrusion 110. In this embodiment, either only the protrusion 110 of the circuit board 400 extends outside the circumference of the hub 202 or both of the protrusion 110 and the heat-dissipative film 106 extend outside the circumference of the hub 202. Even in the case where only the protrusion 110 extends outside the circumference of the hub 202, because the protrusion 110 is located directly in the air passage of the fan structure 200, it is possible to dissipate the heat generated by the heat-generating component 104 by the airflow passing past the protrusion 110. Therefore, it is possible not only for the circuit board 400 to have an enhanced efficiency in heat dissipation and therefore an increased operable current range of the electronic components mounted thereon, but also for the fan structure 200 provided with the circuit board 400 to have a prolonged lifetime.

[0035] Alternatively, the heat-dissipative film 112 on the circuit board 500 is formed on the protrusion 110 as shown in FIG. [[6]] 7, or the heat-generating component 104 is mounted on the protrusion 110 of the circuit board 500 alone. In this case, the heat generated by the heat-generating component 104 can still be dispersed by the air flowing past the protrusion 110. Therefore, it is possible not only for the circuit board 500 to have an enhanced efficiency in heat dissipation and therefore an increased operable current range of the electronic components mounted thereon, but also for the fan structure 200 provided with the circuit board 500 to have a prolonged lifetime.

[0036] Furthermore, in order to enhance the efficiency in heat dissipation of the circuit board 500, a cutout 114 is formed through the protrusion 110 of a circuit board 600 as shown in FIG. [[7]] 8 to extend over

the length of the heat-generating component 104. In this case, a portion of the heat-generating component 104 is exposed to the air passage via the cutout 114. Therefore, according to this embodiment, the heat-generating component 104 is almost entirely exposed to the air passage, thus the heat-generating component 104 has a greater contact area with the airflow. Hence, the heat generated by the heat-generating component 104 is readily dispersed by the air flowing past the protrusion 110. Therefore, it is possible not only for the circuit board 600 to have an enhanced efficiency in heat dissipation and therefore an increased operable current range of the electronic components mounted thereon, but also for the fan structure 200 provided with the circuit board 600 to have a prolonged lifetime.